

Copper Materials for Low Temperature Sintering

MD-200S(powder)
MDP-200(paste)

Characteristic

- Low temperature sintering... Sintered below 200°C
- Conductivity ... Volume resistivity comparable to metallic copper
- Shear strength... Pressureless bonding in an inert atmosphere



powder



paste

Conductivity

Paste formulation

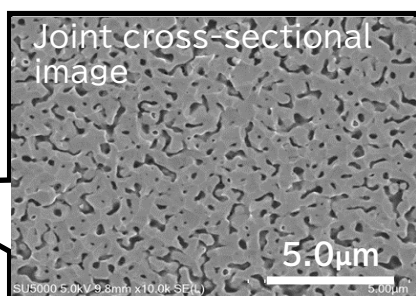
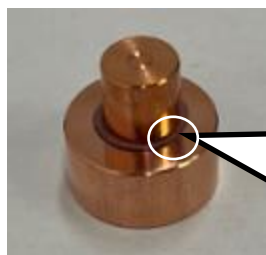
Cu:90wt%
Solvent etc.:10wt%

Sintering conditions

Atmosphere:under nitrogen
Temperature:100~200°C (60min)

	100°C	150°C	200°C
Volume resistivity ($\mu\Omega \cdot \text{cm}$)	< 300	< 25	< 15

Shear strength



Bonding conditions

Test pieces:Cu-Cu
Bonding pressure:pressureless
Atmosphere:under nitrogen
Temperature:100°C/10min
→ 150 or 200°C/20min

	150°C	200°C
Shear strength (MPa)	> 25	> 50

※The listed values are based on our tests and are not guaranteed values.